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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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**DZ5S100D0R**

Silicon epitaxial planar type

For surge absorption circuit  
 DZ5J100D in SSMINI5 type package

■ Features

- Excellent rising characteristics of zener current I<sub>Z</sub>
- Low zener operating resistance R<sub>Z</sub>
- Halogen-free / RoHS compliant  
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: 04

■ Basic Part Number :

Dual DZ3X100D (Common anode)

■ Packaging

Embossed type (Thermo-compression sealing) 8 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

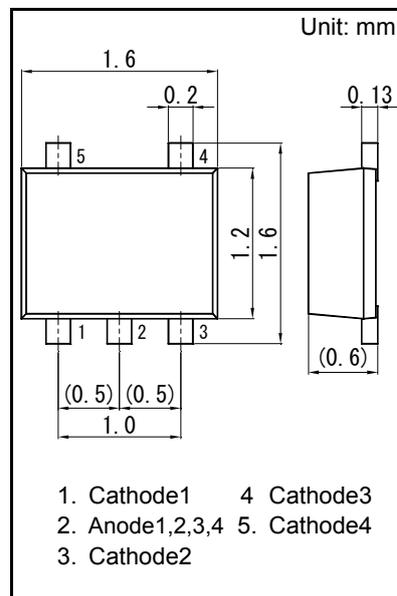
Parameter	Symbol	Rating	Unit
Total power dissipation <sup>*1</sup>	PT	150	mW
Electrostatic discharge <sup>*2</sup>	ESD	±10	kV
Junction temperature	T <sub>J</sub>	150	°C
Operating ambient temperature	T <sub>opr</sub>	-40 to +85	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note) \*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm)

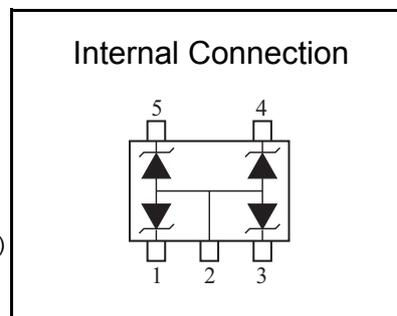
(4Diode total)

Solder in ( 0.35 mm x 0.40 mm)

\*2: Test method:IEC61000\_4\_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)



Panasonic	SSMini5-F4-B
JEITA	SC-107BB
Code	SOT-665



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 10 mA			1.0	V
Zener voltage <sup>*1, *2</sup>	V <sub>Z</sub>	I <sub>Z</sub> = 5 mA	9.50		10.50	V
Zener operating resistance	R <sub>Z</sub>	I <sub>Z</sub> = 5 mA			30	Ω
Zener rise operating resistance	R <sub>ZK</sub>	I <sub>Z</sub> = 0.5 mA			60	Ω
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 7 V			0.05	μA
Temperature coefficient of zener voltage <sup>*3</sup>	SZ	I <sub>Z</sub> = 5 mA		6.5		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

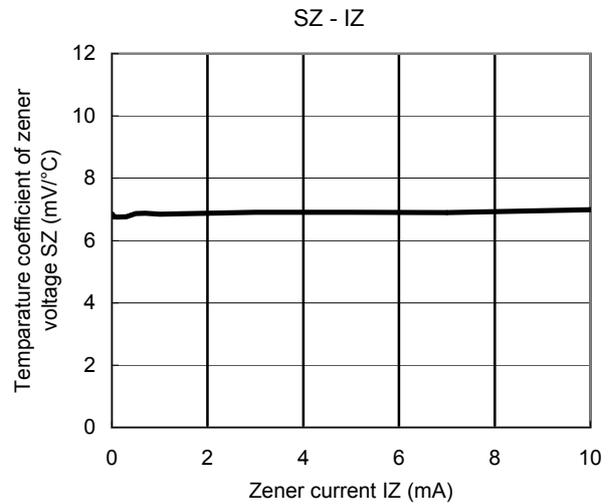
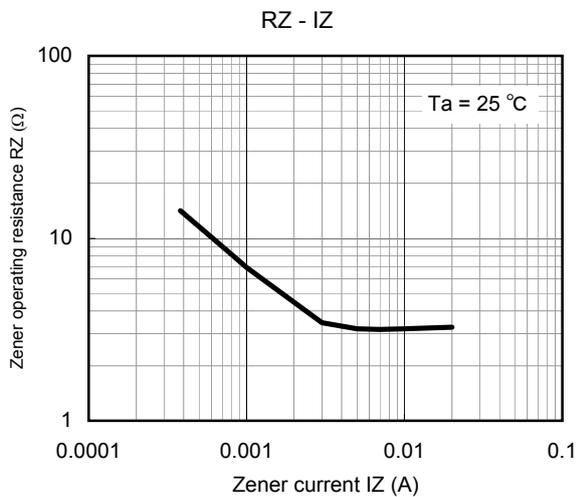
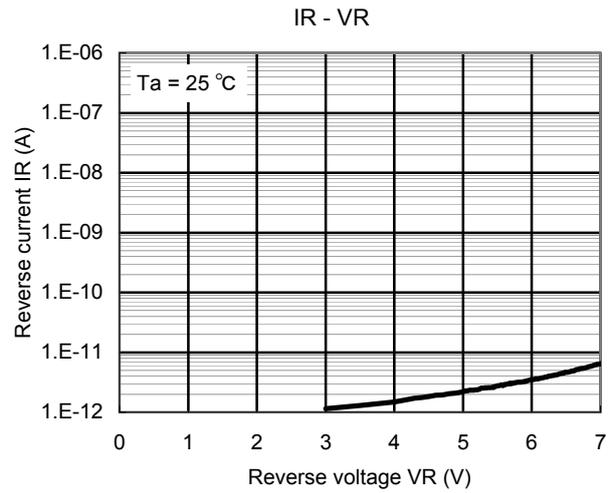
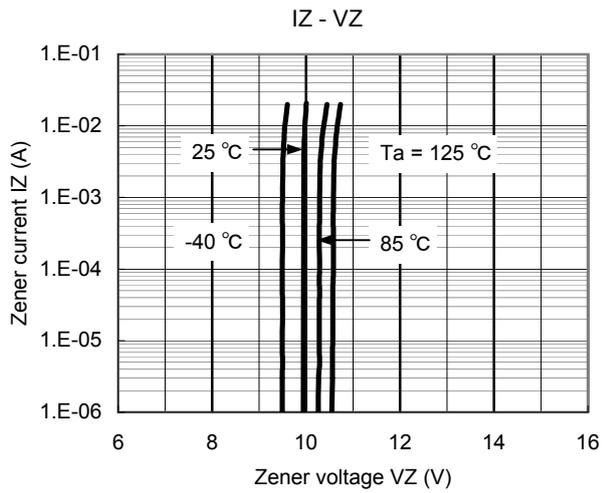
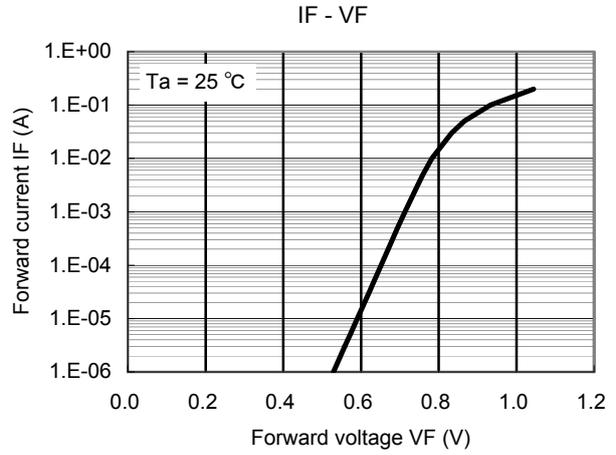
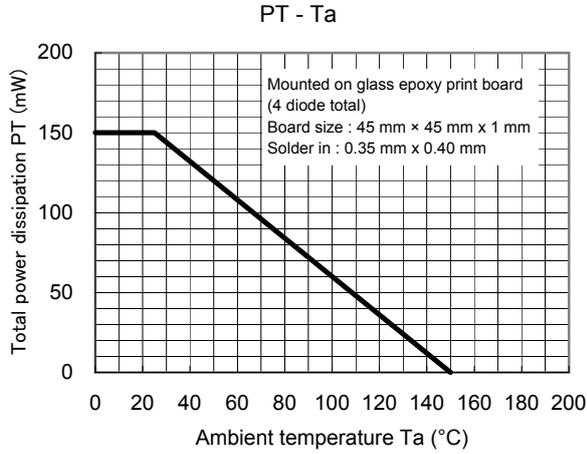
2. \*1: The temperature must be controlled 25°C for V<sub>Z</sub> measurement.

V<sub>Z</sub> value measured at other temperature must be adjusted to V<sub>Z</sub> (25°C)

\*2: V<sub>Z</sub> guaranteed 20 ms after current flow.

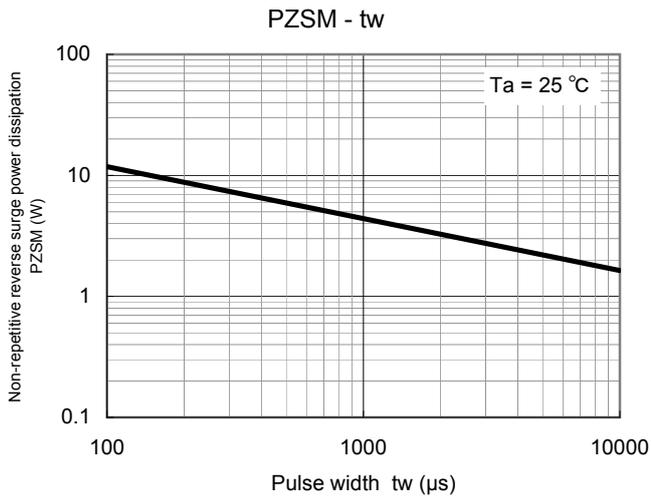
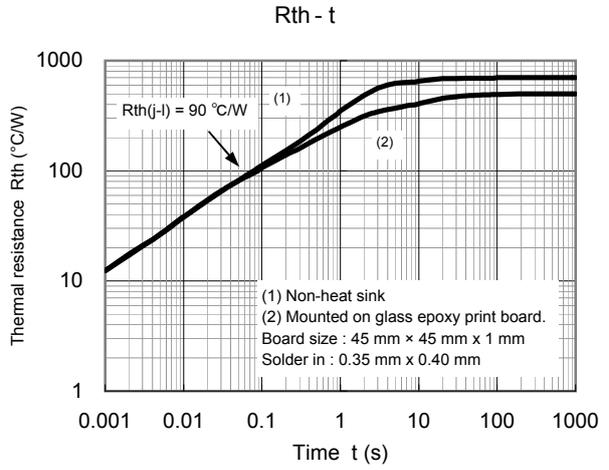
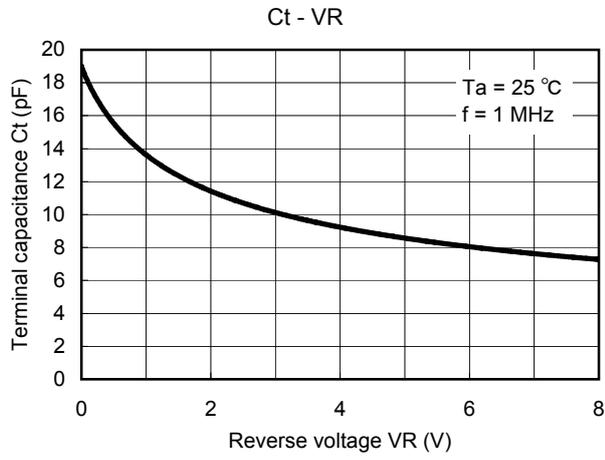
\*3: T<sub>J</sub> = 25°C to 150°C

Technical Data ( reference )



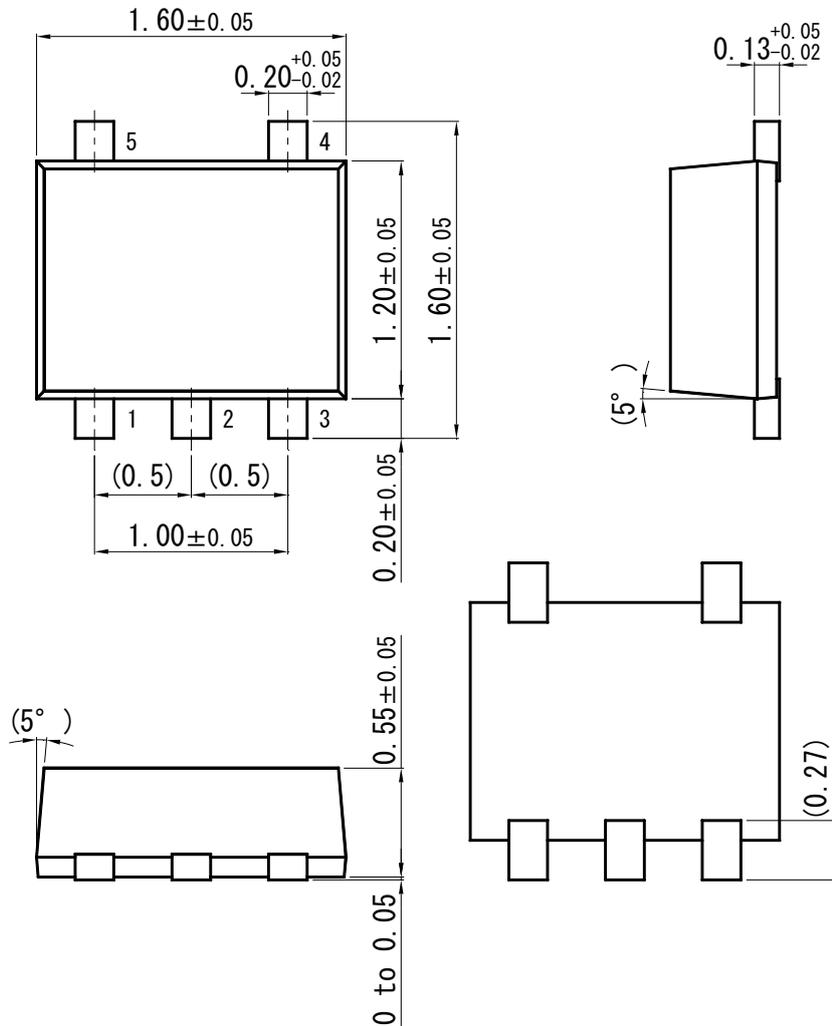


Technical Data ( reference )

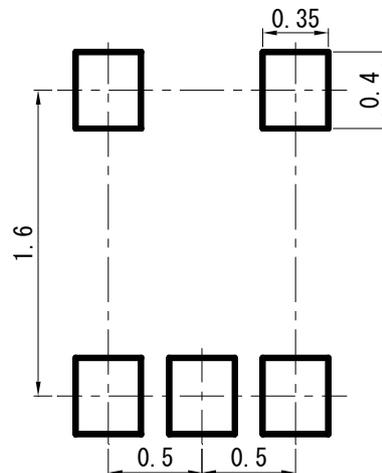


SSMini5-F4-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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